



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

**Akram et al.**

**Serial No.:** 09/241,177

**Filed:** February 1, 1999

**For:** HIGH DENSITY MODULARITY FOR  
IC'S

**Confirmation No.:** 8330

**Examiner:** C. Novacek

**Group Art Unit:** 2822

**Attorney Docket No.:** 2269-3638US  
(98-0093.00/US)

**Notice of Allowance Mailed:**

December 18, 2003

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 9, 2004

Date

Signature

Deidra Pfeil

Name (Type/Print)

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 8 of this paper.